Search Notes					

Application No.	Applicant(s)
10/603,976	JUNG ET AL.
Examiner	Art Unit
Stephen W. Smoot	2813

SEARCHED			
Class	Subclass	Date	Examiner
438	637	7/19/2004	sws
438	675	7/19/2004	sws
438	684	7/19/2004	sws
438	692	7/19/2004	sws
438	693	7/19/2004	sws
252	79.1	7/19/2004	sws
252	79.2	7/19/2004	sws
Updated	Above	12/22/2004	sws &
51	307	12/22/2004	sws 🔏
			,

INTERFERENCE SEARCHED					
Class	Subclass	Date	Examiner		

SEARCH NOTES (INCLUDING SEARCH STRATEGY)						
	DATE	EXMR				
Key Words: CMP - Chemical Mechanical Polishing, Perchloric Acid, Chloric Acid, Hypochlorous Acid,	7/19/2004	INJ, sws				
Bromic Acid, Perbromic Acid, Iodic Acid, Periodic Acid, Hard Pad;	7/19/2004	I.W.S., sws				
Wordline - Polysilicon, Nitride Mask, Spacer, Contact Hole, Interlayer - BPSG, FSG, USG, PSG, TEOS.	7/19/2004	S.U.S.,				
Updated Above Search	12/22/2004	\$.W.\$. sws				
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	7/19/2004 & 12-22-04	sws S.D.L.				
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